

8-bit Microcontroller

# GENERAL DESCRIPTION

This LSI is a high performance CMOS 8-bit microcontroller equipped with an 8-bit CPU nX-U8/100 and integrated with peripheral functions such as synchronous serial port, UART, melody driver, and Analog compartor.

The CPU nX-U8/100 is capable of efficient instruction execution in 1-intruction 1-clock mode by 3-stage pipe line architecture parallel processing. Additionally, it adopts the low-/high-speed dual clock system, standby mode, and process that prohibits leak current at high temperatures, and is most suitable for battery-driven applications.

MTP version can rewrite programs on-board, which can contribute to reduction in product development TAT. The flash memory incorporated into this MTP version implements the mask ROM-equivalent low-voltage operation (1.25V or higher) and low-power consumption (typically 5uA at low-speed operation), enabling volume production by the MTP version. For industrial use, ML610Q485P with the extended operating ambient temperature ranging from -40°C to 85°C are available.

# FEATURES

#### • CPU

- 8-bit RISC CPU (CPU name: nX-U8/100)
- Instruction system: 16-bit length instruction
- Instruction set: Transfer, arithmetic operations, comparison, logic operations, multiplication/division, bit manipulations, bit logic operations, jump, conditional jump, call return stack manipulations, arithmetic shift, and so on
- On-Chip debug function
- Minimum instruction execution time 30.5 μs (@ 32.768 kHz system clock) 2 μs (@ 500 kHz system clock)

0.25 µs (@ 4 MHz system clock)

- Internal memory
  - Internal 32KByte flash memory (16K x 16 bits) (including unusable 1K Byte TEST area)
  - Internal 2KByte RAM (2048 x 8 bits)
- Interrupt controller
- 1 non-maskable interrupt source: Internal source: 1 (Watchdog Timer)
- 28 maskable interrupt sources: Internal source: 16 (SSIO0, Timer0, Timer1, Timer 2, Timer 3, Timer C, Timer D, UART0, Melody 0, PWM0, TBC128Hz, TBC32Hz, TBC16Hz, TBC2Hz, Analog Comparator, RTC)
  External source: 12 (P00, P01, P02, P03, P50, P51, P52, P53, P54, P55, P56, P57) (One interrupt request is generated from P50 to P57 interrupt sources.)
- Time base counter
- Low-speed time base counter x 1 channel
   Frequency compensation (Compensation range: Approx. -488ppm to +488ppm. Compensation accuracy: Approx. 0.48ppm)
- High-speed time base counter x 1 channel
- Real time clock
- Year, month, day, hour, minute, and second registers
- Adjustable to compensate for crystal variations
- Automatic leap year correction
- Regular interrupts (0.5 sec, 1 sec, 1 minute)



- Watchdog timer
- Non-maskable interrupt and reset
- Free running
- Overflow period: 4 types selectable (125ms, 500ms, 2s, 8s)
- Timers
- 8 bits x 6 channels [also available is 16-bit x 3 configuration (using Timers 0-1, 2-3, or C-D) ]
- Clock frequency measurement function mode (16-bit configuration using Timers 2 and 3 x 1 channel only)
- The timer C and timer D are controlled by the external trigger.
- The timer C and timer D are used for the one-shot timer mode.
- PWM
- Resolution 16 bits  $\times$  1 channel
- Capture
- Time base capture x 2 channels (4096 Hz to 32 Hz)
- Synchronous serial port
- Master/slave selectable × 1 channel
- LSB first/MSB first selectable
- 8-bit length/16-bit length selectable
- UART
- TXD/RXD  $\times$  1 channel
- Bit length, parity/no parity, odd parity/even parity, 1 stop bit/2 stop bits
- Positive logic/negative logic selectable
- Built-in baud rate generator
- Melody driver
- Scale: 29 types (Melody sound frequency: 508 Hz to 32.768 kHz)
- Tone length: 63 types
- Tempo: 15 types
- Buzzer output mode (4 output modes, 8 frequencies, 16 duty levels)
- Analog Comparator
- Operating voltage:  $V_{DD}=1.8V\sim3.6V$
- Common mode input voltage:  $0.2V \sim VDD 0.2V$
- Input offset voltage:
- Interrupt allow edge selection and sampling selection
- The RC discharged type A/D convertor is configured with the timers C and D.

30mV(max)

- The temperature measurement function using built-in temperature sensor.
- Temperature measurement range:  $-20^{\circ}$ C to  $+70^{\circ}$ C (P version:  $-40^{\circ}$ C to  $+85^{\circ}$ C)
- The reference voltage can be switched between CMPP0, CMPP1, CMPM0, CMPM1, 1/4VDD, 1/2VDD, temperature sensor and the internal 0.7V voltage source.
- General-purpose ports
  - Input-only port: 4 channels (including secondary functions)
  - Output-only port: 6 channels (including secondary functions)
  - Input/output port: 16 channels (including secondary functions)

- Random Number Generator
- Ring oscillator based entropy source
- Reset
  - Reset through the RESET\_N pin
  - Power-on reset generation when powered on
  - Reset by the watchdog timer (WDT) overflow
  - Reset by the low-speed oscillation stop detection
- Clock
- Low-speed clock (Operation of this LSI is not guaranteed under a condition with no supply of low-speed crystal oscillation clock)
- Crystal oscillation (32.768 kHz)
- High-speed clock
- Built-in RC oscillation (500 kHz, 4 MHz)
- Power management

• Shipment

- HALT mode: Suspends the instruction execution by CPU (peripheral circuits are in operating states)
- STOP mode: Stops the low-speed oscillation and high-speed oscillation (Operations of CPU and peripheral circuits are stopped.)
- High-speed clock gear: The frequency of high-speed system clock can be changed by software (1/1, 1/2, 1/4, or 1/8 of the oscillation clock)
- Block control function: Completely stops the operation of any function block circuit that is not used (resets registers and stops clock)
- When LSCLK is selected for system clock, the power consumption can be reduced by using halver circuit.

- Chip (Die) -	Low-speed oscillation stop detect reset	Operating temperature	Product availability
ML610Q485-xxxWA	Yes	-20°C to +70°C	Yes
ML610Q485P-xxxWA	Yes	-40°C to +85°C	Yes

- 48 pin plastic TQFP -	Low-speed oscillation stop detect reset	Operating temperature	Product availability
ML610Q485-xxxTB	Yes	-20°C to +70°C	-
ML610Q485P-xxxTB	Yes	-40°C to +85°C	-

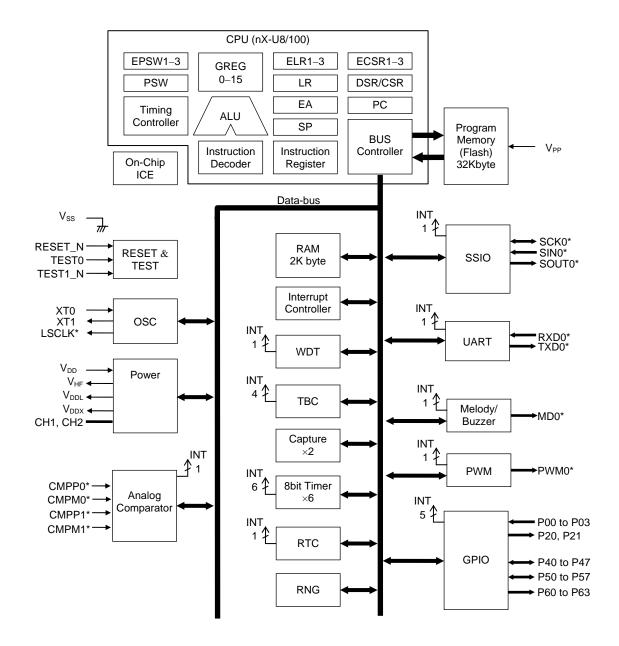
xxx: ROM code number (xxx of the blank product is NNN)Q: MTP versionP: Wide range temperature version (P version)WA: Chip (Die)TB: TQFP

Guaranteed Operation Range

- Operating temperature:  $-20^{\circ}$ C to  $+70^{\circ}$ C (P version:  $-40^{\circ}$ C to  $+85^{\circ}$ C)
- Operating voltage:  $V_{DD} = 1.25V$  to 3.6V (2.4V to 3.6V used halver circuit)

# **BLOCK DIAGRAM**

## **Block Diagram of ML610Q485**

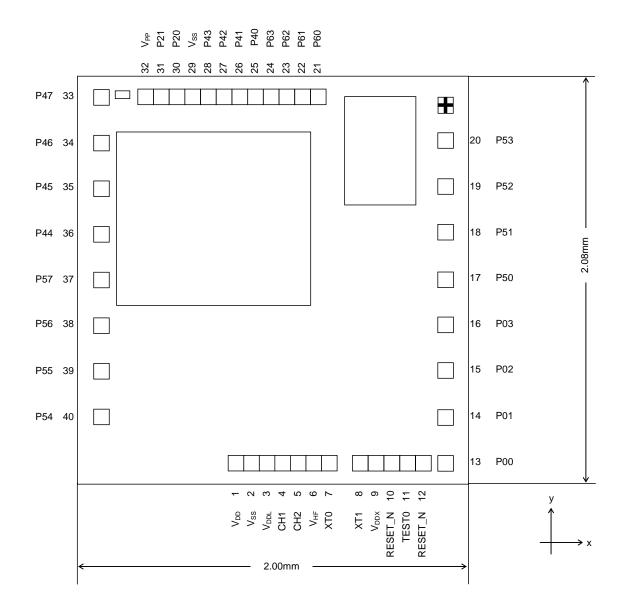


\* Secondary function or Tertiary function

Figure 1 ML610Q485 Block Diagram

# **CHIP PAD LAYOUT**

ML610Q485 Chip Pad Layout & Dimension



Chip size: 2.00mm × 2.08mm PAD count: 40 pins Minimum PAD pitch: 80µm PAD aperture: 70µm×70µm Chip thickness: 350µm Voltage of the rear side of chip: V<sub>SS</sub> level.

Figure 2 ML610Q485 Chip Pin Layout & Dimension

# PAD COORDINATES

# ML610Q485 Pad Coordinates

		1 a	DIE I MILOIUQ48	5 Pau Cool	umates		
						Chip	Center: X=0,Y=0
PAD	Pad	ML61	)Q485	PAD	Pad	ML61	DQ485
No.	Name	X (µm)	Υ (μm)	No.	Name	X (μm)	Y (µm)
1	V <sub>DD</sub>	-193	-934	21	P60	230	934
2	Vss	-113	-934	22	P61	150	934
3	V <sub>DDL</sub>	-33	-934	23	P62	70	934
4	CH1	47	-934	24	P63	-10	934
5	CH2	127	-934	25	P40	-90	934
6	V <sub>HF</sub>	207	-934	26	P41	-170	934
7	XT0	287	-934	27	P42	-250	934
8	XT1	447	-934	28	P43	-330	934
9	V <sub>DDX</sub>	527	-934	29	V <sub>SS</sub>	-410	934
10	RESET_N	607	-934	30	P20	-490	934
11	TEST0	687	-934	31	P21	-570	934
12	TEST1_N	767	-934	32	$V_{PP}$	-650	934
13	P00	879	-934	33	P47	-879	934
14	P01	879	-699	34	P46	-879	699
15	P02	879	-464	35	P45	-879	464
16	P03	879	-229	36	P44	-879	229
17	P50	879	6	37	P57	-879	-6
18	P51	879	241	38	P56	-879	-241
19	P52	879	476	39	P55	-879	-476
20	P53	879	711	40	P54	-879	-711

#### Table 1 ML610Q485 Pad Coordinates

# PIN LIST

PAD		Pri	mary function	Seco	ondary func	tion or	Tertiary function
No.	Pin name	I/O	Function	Secondary/ Tertiary	Pin name	I/O	Function
2,29	V <sub>ss</sub>	_	Negative power supply pin				
1	V <sub>DD</sub>		Positive power supply pin		_	_	
6	V <sub>HF</sub>		Power supply pin for halver circuit (internally generated)		_		
3	V <sub>DDL</sub>		Power supply pin for internal logic (internally generated)				
9	V <sub>DDX</sub>	_	Power supply pin for low-speed oscillation (internally generated)	_	_		
32	V <sub>PP</sub>		Power supply pin for Flash ROM			_	
4	CH1	_	Capacitor connection pin for halver circuit	_		_	—
5	CH2		Capacitor connection pin for halver circuit	_			
11	TEST0	I/O	Test pin			_	
12	TEST1_N	Ι	Test pin			_	
10	RESET_N	—	Reset input pin				
7	XT0	- 1	Low-speed clock oscillation pin				
8	XT1	0	Low-speed clock oscillation pin			—	
13	P00/EXI0/ CAP0/TPRUN0	I	Input port, External interrupt, Capture 0 input Timer C/Timer D external trigger input	—	_	_	—
14	P01/EXI1/ CAP1/TPRUN1	I	Input port, External interrupt, Capture 1 input Timer C/Timer D external trigger input	_	_	_	_
15	P02/EXI2/ RXD0/TPRUN2	Ι	Input port, External interrupt, UART0 received data Timer C/TimerD external trigger input	_	_	_	—
16	P03/EXI3/ TPRUN3	I	Input port, External interrupt Timer C/Timer D external trigger input	—	—	_	—
30	P20/LED0	0	Output port	Secondary	LSCLK	0	Low-speed clock output
31	P21/LED1	0	Output port	Secondary	OUTCLK	0	High-speed clock output
25	P40	I/O	Input/output port	 Tertiary	 SIN0		 SSIO0 data input
26	P41	I/O	Input/output port	 Tertiary			SSIO0 synchronous clock input/output
	_			Secondary	RXD0	1	UART data input
27	P42	1/0	Input/output port	Tertiary	SOUT0	0	SSIO0 data output
20	D40	1/0	Insut/outsut port	Secondary	TXD0	0	UART data output
28	P43	I/O	Input/output port	Tertiary	PWM0	0	PWM output
	P44/T02P0CK/		Input/output port, Timer 0/Timer 2/PWM 0 external			_	
36	TCDRUN	I/O	clock input Timer C/Timer D external trigger Input	Tertiary	SIN0	I	SSIO0 data input
35	P45/T13CK/	I/O	Input/output port, Timer 1/Timer 3 external clock input				
	TCDRUN		Timer C/Timer D external trigger input	Tertiary	SCK0	I/O	SSIO0 synchronous clock input/output
34	P46/TCCK	I/O	Input/output port, Timer C external clock input	 Tertiary		0	 SSIO0 data output
33	P47/TDCK	I/O	Input/output port, Timer D external clock input			_	
17	P50/EXI8	I/O	Input/output port, External interrupt	Secondary	MD0	0	Melody 0 output
18	P51/EXI8	I/O	Input/output port, External interrupt			_	
19	P52/EXI8	I/O	Input/output port, External interrupt		_	_	_

PAD		Pri	mary function	Seco	ondary func	tion or	Tertiary function
No.	Pin name	I/O	Function	Secondary/ Tertiary	Pin name	I/O	Function
20	P53/EXI8	I/O	Input/output port, External interrupt		—	_	—
40	P54/EXI8/ CMPP0	I/O	Input/output port, External interrupt Analog comparator noninverting input0 pin	_	_	_	—
39	P55/EXI8/ CMPP1	I/O	Input/output port, External interrupt Analog comparator noninverting Input1 pin	_	_		—
38	P56/EXI8/ CMPM0	I/O	Input/output port, External interrupt Analog comparator inverting input0 pin	_			—
37	P57/EXI8/ CMPM1	I/O	Input/output port, External interrupt Analog comparator inverting Input1 pin	_		_	—
21	P60	0	Output port		_	_	
22	P61	0	Output port	_		_	
23	P62	0	Output port		—	—	—
24	P63	0	Output port				

# PIN DESCRIPTION

Pin name	I/O	Description	Primary/	
			Secondary/	Logic
			Tertiary	
System				
RESET_N	I	Reset input pin. When this pin is set to a "L" level, system reset mode is set and the internal section is initialized. When this pin is set to a "H" level subsequently, program execution starts. A pull-up resistor is internally connected.	_	Negative
ХТО	Ι	Crystal connection pin for low-speed clock. A 32.768 kHz crystal resonator is connected to this pin. Capacitors	—	—
XT1	0	$C_{\text{DL}}$ and $C_{\text{GL}}$ are connected across this pin and $V_{\text{SS}}.$ (see appendix C measuring circuit 1)	—	—
LSCLK	0	Low-speed clock output. Assigned to the secondary function of the P20 pin.	Secondary	—
OUTCLK	0	High-speed clock output pin. This pin is used as the secondary function of the P21 pin.	Secondary	—
General-purpos	se input	port		
P00 to P03	Ι	General-purpose input port.	Primary	Positive
General-purpos	se outpu	ut port		
P20, P21	0	General-purpose output port. This cannot be used as the general output port when used as the secondary function.	Primary	Positive
P60 to P63	0	General-purpose output port.	Primary	Positive
General-purpos	se input	/output port		
P40 to P47	I/O	General-purpose input/output port.		
		This cannot be used as the general input/output port when used as the secondary or tertiary function.	Primary	Positive
P50 to P57	I/O	General-purpose input/output port. This cannot be used as the general input/output port when used as the secondary function.	Primary	Positive

			Primary/	
Pin name	I/O	Description	Secondary/	Logic
		·	Tertiary	5
UART				
TXD0	0	UART data output pin. This pin is used as the secondary function of the P43 pin.	Secondary	Positive
RXD0	I	UART data input pin. This pin is used as the secondary function of the P42 or the primary function of the P02 pin.	Primary/ Secondary	Positive
Synchronous se	rial (S	SIO)		
SCK0	I/O	Synchronous serial clock input/output pin. This pin is used as the tertiary function of the P41 or P45 pin.	Tertiary	
SIN0	I	Synchronous serial data input pin. This pin is used as the tertiary function of the P40 or P44 pin.	Tertiary	Positive
SOUT0	0	Synchronous serial data output pin. This pin is used as the tertiary function of the P42 or P46 pin.	Tertiary	Positive
External interrup	ot			
EXI0-3	I	External maskable interrupt input pins. Interrupt enable and edge selection can be performed for each bit by software. These pins are used as the primary functions of the P00 to P03 pins.	Primary	Positive/ negative
EXI8	I	External maskable interrupt input pins. Interrupt enable and edge selection can be performed for each bit by software. Assigned to the primary function of the P50 to P57 pins.	Primary	Positive/ negative
Capture				
CAP0	I	Capture trigger input pins. The value of the time base counter is captured in the register synchronously with the interrupt edge	Primary	Positive/ negative
CAP1	I	selected by software. These pins are used as the primary functions of the P00 pin(CAP0) and P01 pin(CAP1).	Primary	Positive/ negative
Timer				5
T02P0CK	I	External clock input pin used for both Timer 0 and Timer 2. This pin is used as the primary function of the P44 pin.	Primary	—
T13CK	I	External clock input pin used for both Timer 1 and Timer 3. This pin is used as the primary function of the P45 pin.	Primary	_
ТССК	Ι	External clock input pin used for Timer C. This pin is used as the primary function of the P46 pin.	Primary	
TDCK	I	External clock input pin used for Timer D. This pin is used as the primary function of the P47 pin.	Primary	_
TCDRUN	I	External trigger input pin used for Timer C or Timer D. This pin is used as the primary function of the P44 pin or the P45 pin.	Primary	_
TPRUN0	I	External trigger input pin used for Timer C or Timer D. This pin is used as the primary function of the P00 pin.	Primary	
TPRUN1	I	External trigger input pin used for Timer C or Timer D. This pin is used as the primary function of the P01 pin.	Primary	_
TPRUN2	I	External trigger input pin used for Timer C or Timer D. This pin is used as the primary function of the P02 pin.	Primary	
TPRUN3	Ι	External trigger input pin used for Timer C or Timer D. This pin is used as the primary function of the P03 pin.	Primary	—
LED drive				
LED0, LED1	0	N-channel open drain output pins to drive LED. This pin is used as the primary function of the P20 and the P21 pins.	Primary	Positive /negative

			Primary/	
Pin name	I/O	Description	Secondary/	Logic
			Tertiary	
Melody				
MD0	0	Melody/buzzer signal output pin. This pin is used as the secondary	Secondary	Positive/
		function of the P50 pin.		negative
PWM				
PWM0	0	PWM0 output pin. This pin is used as the tertiary function of the P43 pin.	,	Positive
T02P0CK	I	PWM0 external clock input pin. This pin is used as the primary function of the P44 pin.	Primary	—
Analog Compa	rator			
CMPP0	I	Analog comparator noninverting input0 pin. This pin is used as the primary function of the P54.	Primary	—
CMPP1	I	Analog comparator noninverting input1 pin. This pin is used as the primary function of the P55.	Primary	—
CMPM0	I	Analog comparator inverting input0 pin. This pin is used as the primary function of the P56.	Primary	—
CMPM1	I	Analog comparator inverting input1 pin. This pin is used as the primary function of the P57.	Primary	—
Test				
TEST0	I/O	Pin for testing. A pull-down resistor is internally connected.	_	Positive
TEST1_N	Ι	Pin for testing. A pull-up resistor is internally connected.		Negative
Power supply				
V <sub>SS</sub>	—	Negative power supply pin.	_	—
V <sub>DD</sub>	_	Positive power supply pin.	_	—
V <sub>HF</sub>	—	Positive power supply pin (internally generated) for Halver. Capacitor CHF (see measuring circuit 1) should be connected between this pin and Vss.		
V <sub>DDL</sub>	_	Positive power supply pin (internally generated) for internal logic. Capacitors $C_L$ (see measuring circuit 1) are connected between this pin and $V_{SS}$ .		—
V <sub>DDX</sub>	_	Positive power supply pin (internally generated) for low-speed oscillation. Capacitor Cx (see measuring circuit 1) should be connected		
CH1	-	between this pin and Vss. Capacitor connection pin for halver circuit.		
CH2	-	Capacitor $C_{H12}$ (see measuring circuit 1) are connected between CH1 and CH2.		
V <sub>PP</sub>	—	Power supply pin for programming Flash ROM. A pull-down resistor is internally connected.	_	—

## TERMINATION OF UNUSED PINS

Table 2 shows methods of terminating the unused pins.

Pin	Recommended pin handling
V <sub>PP</sub>	Open
RESET_N	Open
TEST0	Open
TEST1_N	Open
P00 to P03	V <sub>DD</sub> or V <sub>SS</sub>
P20, P21	Open
P40 to P47	Open
P50 to P57	Open
P60 to P63	Open

#### Table 2 Termination of Unused Pins

Note:

It is recommended to set the unused input ports and input/output ports to the inputs with pull-down resistors/pull-up resistors or the output mode since the supply current may become excessively large if the pins are left open in the high impedance input setting.

# **ELECTRICAL CHARACTERISTICS**

# **Absolute Maximum Ratings**

	-			(V <sub>SS</sub> = 0V
Parameter	Symbol	Condition	Rating	Unit
Power supply voltage 1	V <sub>DD</sub>	Ta=25°C	-0.3 to +4.6	V
Power supply voltage 2	V <sub>PP</sub>	Ta=25°C	-0.3 to +9.5	V
Power supply voltage 3	V <sub>DDL</sub>	Ta=25°C	-0.3 to +3.6	V
Input voltage	V <sub>IN</sub>	Ta=25°C	-0.3 to V <sub>DD</sub> +0.3	V
Output voltage	Vout	Ta=25°C	-0.3 to V <sub>DD</sub> +0.3	V
Output current 1	I <sub>OUT1</sub>	Port 4 to 6, Ta=25°C	-12 to +11	mA
Output current 2	I <sub>OUT2</sub>	Port 2, Ta=25°C	-12 to +20	mA
Power dissipation	PD	Ta=25°C	0.9	W
Storage temperature	T <sub>STG</sub>		-55 to +150	°C

# **Recommended Operating conditions**

				$(V_{SS}=0)$
Parameter	Symbol	Condition	Range	Unit
Operating temperature	т	without P version	-20 to +70	*
Operating temperature	T <sub>OP</sub>	P version	-40 to +85	
		f <sub>OP</sub> =30k to 625kHz	1.25 to 3.6	
Operating voltage	V <sub>DD</sub>	f <sub>OP</sub> =30k to 5MHz	1.8 to 3.6	V
		f <sub>OP</sub> =30k to 36kHz, Used Halver	2.4 to 3.6	
		V <sub>DD</sub> =1.25 to 3.6V	30k to 625k	
Operating frequency	fop	V <sub>DD</sub> =1.8 to 3.6V	30k to 5.0M	Hz
(CPU)		V <sub>DD</sub> =2.4 to 3.6V, Used Halver	30k to 36k	
Low-speed crystal oscillation frequency	f <sub>XTL</sub>	—	32.768k	Hz
Low-speed crystal oscillation	C <sub>DL</sub>	—	3 to 18	
external capacitance	$C_{GL}$	_	3 to 18	— pF
V <sub>DDL</sub> pin external capacitance	CL	-	2.2±30%	μF
V <sub>DDX</sub> pin external capacitance	C <sub>x</sub>	_	0.1±30%	μF
V <sub>HF</sub> pin external capacitance	C <sub>HF</sub>	_	0.1±30%	μF
Pin-to-pin (CH1 to CH2) external capacitance	C <sub>H12</sub>	-	0.1±30%	μF

#### **Operating conditions of FlashROM**

				(100-0
Parameter	Symbol	Condition	Range	Unit
Operating temperature	T <sub>OP</sub>	At write/erase	0 to +40	°C
	V <sub>DD</sub>	At write/erase	2.75 to 3.6	
Operating voltage	V <sub>DDL</sub>	At write/erase <sup>*1</sup>	2.5 to 2.75	V
	V <sub>PP</sub>	At write/erase	7.7 to 8.3	
Rewrite count	C <sub>EP</sub>	—	80	cycles
Data retention	Y <sub>DR</sub>	—	10	years

<sup>1</sup>: When writing to and erasing on the flash Memory, the voltage in the specified range needs to be supplied to the V<sub>DDL</sub> pin. The V<sub>PP</sub> pin has an internal pull-down resistor.

#### **Operation conditions of Comparator**

(V<sub>DD</sub>=1.8 to 3.6V, V<sub>SS</sub>=0V, Ta=-20 to +70°C, Ta=-40 to +85°C for P version, unless otherwise specified)

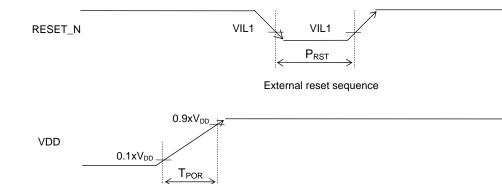
Parameter	Symbol	Condition		Rating			Measurement	
Farameter	Symbol	Condition	Min.	Min. Typ.		Unit	circuit	
Common-mode input voltage	CMV <sub>IN</sub>	—	0.2	_	V <sub>DD</sub> -0.2	V		
Analog Comparator Input offset voltage	V <sub>CMPOF</sub>	Ta=25°C	-30	_	30	mV		
Analog Comparator Response time	T <sub>CMP</sub>	Ta=25°C, Overdrive=100mV		—	1	μs		
Analog Comparator Wakeup time	T <sub>CMPW</sub>	_	_	_	5	μs		
Analog Comparator supply current	I <sub>CMP</sub>	Ta=25°C	_	33	45	μA		
Temperature sensor output voltage through x2	V <sub>TMP</sub>	MP Ta=25°C —		1355	_	mV		
Temperature sensor		Ta = -40 to +25°C	—	-3.585	_		1	
output voltage through x2 (Temperature property)	$\Delta V_{TMP}$	Ta = 25 to 85°C	_	-3.718	—	mV/°C		
0.7V voltage source output voltage through x2	$V_{REF}$	Ta=25°C	1.386	1.400	1.414	V		
0.7V voltage source temperature deviation	$\Delta V_{REF}$	_	_	0	—	%/°C		
0.7V voltage source supply current	I <sub>REF</sub>	Ta=25°C	_	20	40	μA		
1/2 VDD voltage source	VDD2	_	VDD/2 x 0.96	VDD/2	VDD/2 x 1.04	V		
1/4 VDD voltage source	VDD4	_	VDD/4 x 0.96	VDD/4	VDD/4 x 1.04	V		

#### DC Characteristics (1/4)

(VDD=1	.25 to 3.6V,	VSS=0V, Ta=-2	20 to +70°C, Ta	=-40 to +85°	C for P ver	sion, unless	otherwise s	pecified)					
Parameter	Symbol	Condition		DI Condition Rating					Unit	Measure ment			
Falameter	Symbol	Conc	inion	Min.	Тур.	Max.	Unit	circuit					
		V <sub>DD</sub> =1.25	Ta=25°C	Тур. -10%	500	Тур. +10%	kHz						
500kHz/4MHz RC	f <sub>RC</sub>	to 3.6V	*2	Тур. -25%	500	Тур. +25%	kHz						
oscillation frequency		IRC	IRC	IRC	IRC -	IRC	V <sub>DD</sub> =1.8 to	Ta=25°C	Тур. -10%	4.0	Тур. +10%	MHz	
		3.6V		Тур. -25%	4.0	Тур. +25%	MHz						
Low-speed crystal oscillation start time* <sup>1</sup>	T <sub>XTL</sub>	-	_	—	0.6	2	s	1					
500kHz/4MHz RC oscillation start time	T <sub>RC</sub>	-	-	—	—	3	μs						
Reset pulse width	P <sub>RST</sub>	-	-	200	—	—							
Reset noise elimination pulse width	P <sub>NRST</sub>	_	_	_	_	0.3	μs						
Power-on reset generated power rise time	T <sub>POR</sub>	_		_	_	10	ms						

\*<sup>1</sup>: 32.768kHz crystal resonator DT-26 (Load capacitance 6pF) (made by KDS:DAISHINKU CORP.) is used (C<sub>GL</sub>=C<sub>DL</sub>=6pF).
 \*<sup>2</sup>: Recommended operating temperature (Ta=-20 to 70°C, Ta=-40 to 85°C for P version)

Power on reset sequence



#### DC Characteristics (2/4)

		(V <sub>DD</sub> =3.0V, V <sub>SS</sub> =0V, Ta=-20 to +70°0	C, Ta=-40 to	+85°C for		n, unless (	otherwise sp	Decified) Measur
Parameter	Symbol	Condition	Min.	Rating Typ.	Max.	Unit	ement	
Supply current	IDD1	CPU: In STOP state.	Ta=25°C	_	0.32	0.8		
1	וסטו	Low-speed/High-speed oscillation: stopped.	*4	_	_	8	μA	
Supply current		CPU: In HALT state. (LTBC, WDT: Operating)* <sup>2</sup> * <sup>3</sup> .	Ta=25°C	_	0.35	0.7		_
2 IDD2	High-speed 500kHz/4MHz oscillation: Stopped. Used halver	*4	_	_	4	μA		
Supply current	Supply current	CPU: In 32.768kHz operating state.*1*2	Ta=25°C	_	4.5	8		
3-1 IDD3-1	IDD3-1	oscillation: Stopped, *4	_	_	15	μA	1	
Supply current	IDD3-2	Not used halver CPU: In 32.768kHz operating state.* <sup>1*2</sup> High-speed 500kHz/4MHz	Ta=25°C		2.5	4	μA	_
3-2		oscillation: Stopped, Used halver	*4	_	_	7.5		
Supply current	Supply current	CPU: In 500kHz RC operating	Ta=25°C	—	75	100		
4-1	IDD4-1	state. Not used halver	*4	_	_	120	μA	
Supply current	IDD4-2	CPU: In 4MHz RC operating state.	Ta=25°C	_	600	750	μA	1
4-2	-2007-2	Not used halver	*4	_	—	800	μΛ	

\*<sup>1</sup>: When the CPU operating rate is 100% (no HALT state).
 \*<sup>2</sup>: 32.768KHz crystal resonator DT-26 (Load capacitance 6pF) (made by KDS:DAISHINKU CORP.) is used (C<sub>GL</sub>=C<sub>DL</sub>=6pF)
 \*<sup>3</sup>: Significant bits of BLKCON0 to BLKCON3 registers are all "1".
 \*<sup>4</sup>: Recommended operating temperature (Ta=-20 to 70°C, Ta=-40 to 85°C for P version)

				Rating		Unit	Measur
Parameter	Symbol	Condition	Min.	Тур.	Typ. Max.		ement circuit
Output voltage 1 (P20, P21 VOH1		IOH1=-0.5mA, V <sub>DD</sub> =1.8 to 3.6V		_			
(N-channel open drain output mode is not	VOITI	IOH1=-0.03mA, V <sub>DD</sub> =1.25 to 3.6V	V <sub>DD</sub> -0.3		_		
selected)) (P40 to P47)	VOL1	IOL1=+0.5mA, V <sub>DD</sub> =1.8 to 3.6V	_	_	0.5		
(P50 to P57) (P60 to P63)	VOLI	IOL1=+0.1mA, V <sub>DD</sub> =1.25 to 3.6V	_	_	0.3	V	2
Output voltage 2 (P20, P21 (N-channel open drain output mode is selected))		IOL2=+5mA, V <sub>DD</sub> =1.8 to 3.6V	_	_	0.5		
Output leakage (P20, P21) (P40 to P47) (P50 to P57)	IOOH	VOH=V <sub>DD</sub> (in high-impedance state)	_	_	1	μA	3
(P60 to P63)	IOOL	VOL=V <sub>SS</sub> (in high-impedance state)	-1	_	_		
Input current 1	IIH1	VIH1=V <sub>DD</sub>	_	_	1		
(RESET_N, TEST1_N)	IIL1	VIL1=V <sub>SS</sub>	-600	-300	-2		
Input current 2	IIH2	VIH2=V <sub>DD</sub>	2	300	600		
(TEST0)	IIL2	VIL2=V <sub>SS</sub>	-1	—	—		
	IIH3	VIH3=V <sub>DD</sub> , V <sub>DD</sub> =1.8 to 3.6V (when pulled-down)	2	30	200		
Input current 3		VIH3=V <sub>DD,</sub> V <sub>DD</sub> =1.25 to 3.6V (when pulled-down)	0.01	30	200	μA	4
(P00 to P03) (P40 to P47)		VIL3=V <sub>SS</sub> , V <sub>DD</sub> =1.8 to 3.6V (when pulled-up)	-200	-30	-2		
(P50 to P57)	, 1120	VIL3=V <sub>SS</sub> , V <sub>DD</sub> =1.25 to 3.6V (when pulled-up)	-200	-30	-0.01		
	IIH3Z	VIH3=V <sub>DD</sub> (in high-impedance state)	—	—	1	1	
	IIL3Z	VIL3=V <sub>SS</sub> (in high-impedance state)	-1	_	_	1	

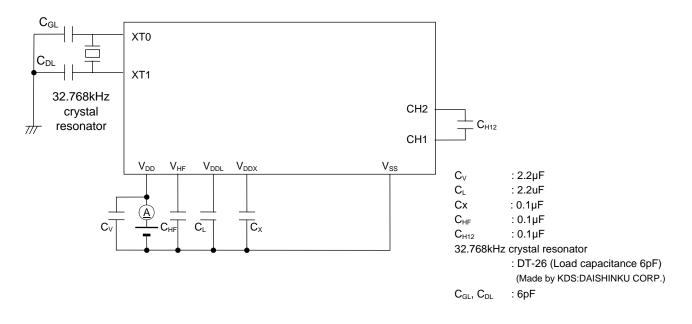
# DC Characteristics (3/4)

# DC Characteristics (4/4)

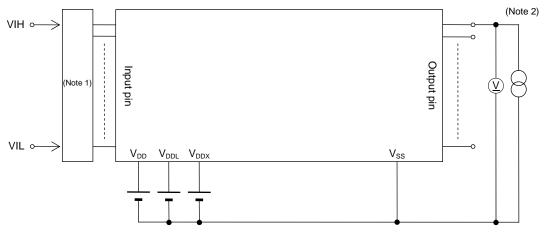
	(VDD=1	.25 to 3.6V, VSS=0V, Ta=-20 to +70°C, Ta=-40 to	+85°C for	P version,	, unless otł	nerwise sp	ecified)
Devenenter	Cumphic	Condition		Rating		Measur	
Parameter	Symbol	bol Condition		Тур.	Max.	Unit	ement circuit
Input voltage 1 (RESET_N) (TEST1_N) (TEST0)	VIH1	_	0.7 ×V <sub>DD</sub>	_	V <sub>DD</sub>	V	5
(P00 to P03) (P40 to P47) (P50 to P57)	VIL1	V <sub>DD</sub> =1.25 to 3.6V	0	_	0.2 ×V <sub>DD</sub>		
Input pin capacitance (P00 to P03) (P40 to P47) (P50 to P57)	CIN	f=10kHz V <sub>rms</sub> =50mV Ta=25°C	_	_	5	pF	_

# **Measuring Circuits**

#### **Measuring Circuit 1**

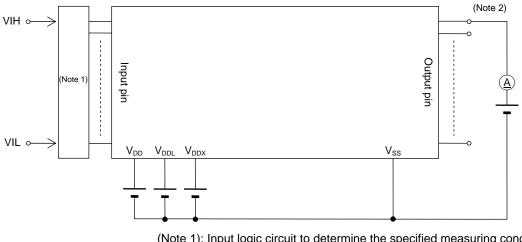


**Measuring Circuit 2** 



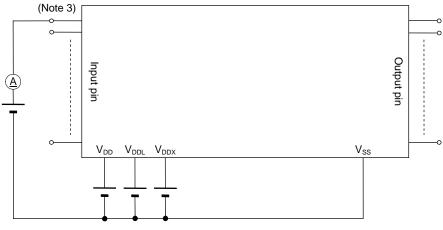
(Note 1): Input logic circuit to determine the specified measuring conditions. (Note 2) Repeats for the specified output pin

## **Measuring Circuit 3**



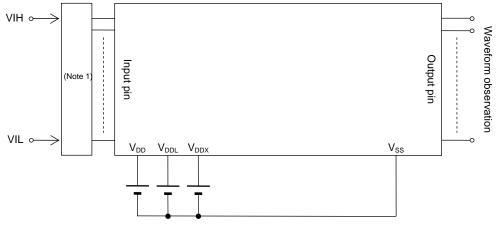
(Note 1): Input logic circuit to determine the specified measuring conditions. (Note 2) Repeats for the specified output pin

### **Measuring Circuit 4**



(Note 3) Repeats for the specified input pin

# **Measuring Circuit 5**

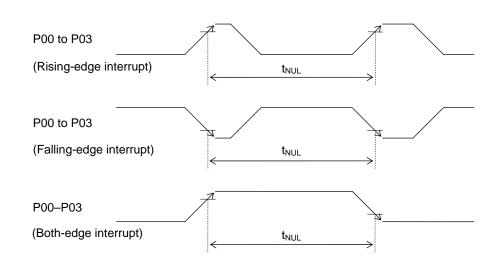


(Note 1): Input logic circuit to determine the specified measuring conditions.

#### AC Characteristics (External Interrupt)

(V<sub>DD</sub>=1.25 to 3.6V, V<sub>SS</sub>=0V, Ta=-20 to +70°C, Ta=-40 to +85°C for P version, unless otherwise specified)

Parameter	Svmbol	Condition		Rating		
Falameter	Symbol		Min. Ty		Max.	Unit
External interrupt disable	T <sub>NUL</sub>	Interrupt: Enabled (MIE = 1), CPU: NOP operation	76.8	_	106.8	μs
penou		System clock: 32.768kHz				

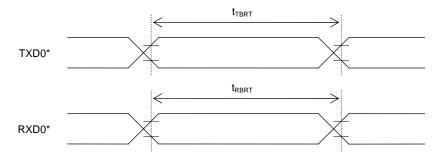


#### **AC Characteristics (UART)**

(V<sub>DD</sub>=1.25 to 3.6V, V<sub>SS</sub>=0V, Ta=-20 to +70°C, Ta=-40 to +85°C for P version, unless otherwise specified)

Parameter	Symbol	Condition		Rating		Unit
 Farameter	Symbol	Condition	Min.	Тур.	Max.	Unit
 Transmit baud rate	t <sub>TBRT</sub>	_	_	BRT* <sup>1</sup>	_	S
 Receive baud rate	t <sub>RBRT</sub>	_	BRT* <sup>1</sup> -3%	BRT* <sup>1</sup>	BRT* <sup>1</sup> +3%	S

\*<sup>1</sup>: Baud rate period (including the error of the clock frequency selected) set with the UART baud rate register (UA0BRTL,H) and the UART mode register 0 (UA0MOD0).



\*: Indicates the secondary function of the port.

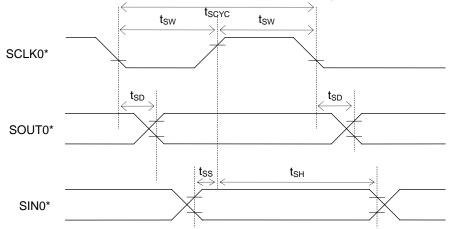
## AC CHARACTERISTICS (Synchronous Serial Port)

$(V_{DD} = 1.25 \text{ to } 3.6V, V_{SS} = 0V, Ta = -20 \text{ to } +70^{\circ}\text{C}, Ta = -40 \text{ to } +85^{\circ}\text{C}$ for P version, unless otherwis	specified)
---	------------

Parameter	Symbol	Condition		Unit		
Falameter	Symbol	Condition	Min.	Тур.	Max.	Unit
SCLK0 input cycle	tanya	When RC oscillation is 500kHz $*^{2}$ (V <sub>DD</sub> = 1.25 to 3.6V)	10			
(slave mode)	t <sub>SCYC</sub>	When RC oscillation is 4MHz $*^3$ (V <sub>DD</sub> = 1.8 to 3.6V)	2			μS
SCLK0 output cycle (master mode)	tscyc	—		SCLK0*1		S
SCLK0 input pulse width		When RC oscillation is 500kHz $*^{2}$ (V <sub>DD</sub> = 1.25 to 3.6V)	4			
(slave mode)	t <sub>SW</sub>	When RC oscillation is 4MHz $*^3$ (V <sub>DD</sub> = 1.8 to 3.6V)	04			μS
SCLK0 output pulse width (master mode)	t <sub>SW</sub>		SCLK0* <sup>1</sup> ×0.4	SCLK0* <sup>1</sup> ×0.5	SCLK0* <sup>1</sup> ×0.6	S
SOUT0 output delay time		When RC oscillation is 500kHz * <sup>2</sup> (V <sub>DD</sub> = 1.25 to 3.6V) output load 10pF		_	500	
(slave mode)	t <sub>SD</sub>	When RC oscillation is 4MHz * <sup>3</sup> ( $V_{DD}$ = 1.8 to 3.6V) output load 10pF			240	ns
SOUT0 output delay time		When RC oscillation is 500kHz * <sup>2</sup> (V <sub>DD</sub> = 1.25 to 3.6V) output load 10pF			500	
(master mode)	t <sub>SD</sub>	When RC oscillation is 4MHz * <sup>3</sup> ( $V_{DD}$ = 1.8 to 3.6V) output load 10pF			240	ns
SIN0 input setup time (slave mode)	tss		80			ns
SIN0 input setup time		When RC oscillation is 500kHz $*^{2}$ (V <sub>DD</sub> = 1.25 to 3.6V)	500	_	_	
(master mode)	t <sub>SS</sub>	When RC oscillation is 4MHz $*^3$ (V <sub>DD</sub> = 1.8 to 3.6V)	240			ns
SINO input hold time		When RC oscillation is 500kHz $*^2$ (V <sub>DD</sub> = 1.25 to 3.6V)	300			
SIN0 input hold time	t <sub>SH</sub>	When RC oscillation is 4MHz $*^3$ (V <sub>DD</sub> = 1.8 to 3.6V)	80			ns

\*1: Clock period selected with S0CK3–0 of the serial port n mode register (SIO0MOD1) \*<sup>2</sup>: When 500kHz RC oscillation is selected by OSCM3 of the frequency control register (FCON0)

\*<sup>3</sup>: When 4MHz RC oscillation is selected by OSCM3 of the frequency control register (FCON0)



\*: Indicates the secondary function of the port

# **REVISION HISTORY**

		Pa	ge	
Document No.	Date	Previous	Current	Description
		Edition	Edition	
FEDL610Q485-01	Aug.25,2014	_	_	Final edition 1

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